



N-Channel Enhancement Mode Power MOSFET

Description

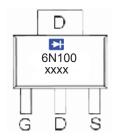
The RM6N100S4V uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

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Schematic diagram

General Features

- $V_{DS} = 100V, I_D = 6A$ $R_{DS(ON)} < 140m\Omega @ V_{GS} = 10V$ (Typ:110m Ω)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation



Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free
- P/N suffix V means AEC-Q101 qualified

SOT-223 top view

Package Marking and Ordering Information

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Device Marking	Device	Device Package	Reel Size	Tape width	Quantity	
6N100	RM6N100S4V	SOT-223-3L	Ø330mm	12mm	2500 units	

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	6	А
Drain Current-Pulsed (Note 1)	I _{DM}	24	Α
Maximum Power Dissipation	P _D	3	W
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	41.7	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA

Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA		
On Characteristics (Note 3)								
Gate Threshold Voltage V _{GS(th}		$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.8	2.5	V		
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5A	-	110	140	mΩ		
Forward Transconductance	g FS	V _{DS} =5V,I _D =2.9A	-	8	-	S		
Dynamic Characteristics (Note4)	·		_					
Input Capacitance	C _{lss}	V _{DS} =25V,V _{GS} =0V,	-	690	-	PF		
Output Capacitance	C _{oss}	F=1.0MHz	-	120	-	PF		
Reverse Transfer Capacitance	C _{rss}	F=1.0WI1Z	-	90	-	PF		
Switching Characteristics (Note 4)								
Turn-on Delay Time	t _{d(on)}		-	11	-	nS		
Turn-on Rise Time	t _r	V_{DD} =30 V , I_D =2 A , R_L =15 Ω	-	7.4	1	nS		
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{G} =2.5 Ω	-	35	-	nS		
Turn-Off Fall Time	t _f		-	9.1	-	nS		
Total Gate Charge	Qg	\/ 20\/ 24	-	15.5		nC		
Gate-Source Charge	V _{DS} =30V,I _D =3A,		-	3.2	-	nC		
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	4.7	-	nC		
Drain-Source Diode Characteristics								
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	-	1.2	V		
Diode Forward Current (Note 2)	Is		-	-	6	Α		
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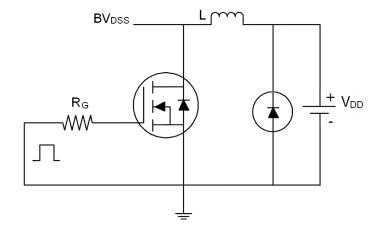
Notes:

- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to product

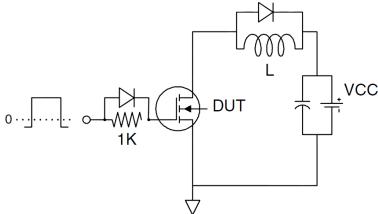


Test Circuit

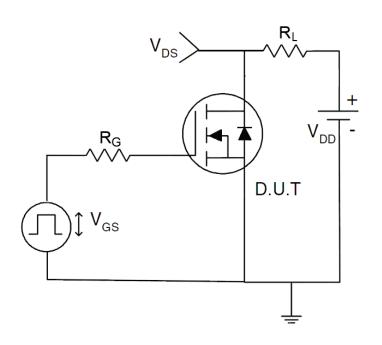
1) E_{AS} test circuit



2) Gate charge test circuit



3) Switch Time Test Circuit





RATING AND CHARACTERISTICS CURVES (RM6N100S4V)

Figure 1. Source-Drain Diode Forward Voltage

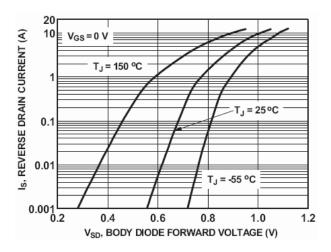


Figure 3. Output characteristics

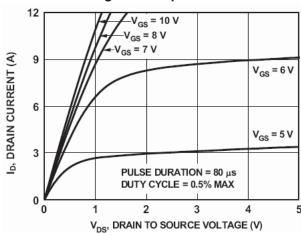


Figure 5. Static drain-source on resistance

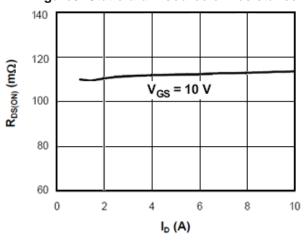


Figure 2. Safe operating area

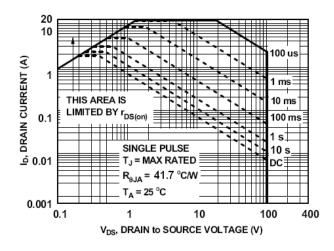


Figure 4. Transfer characteristics

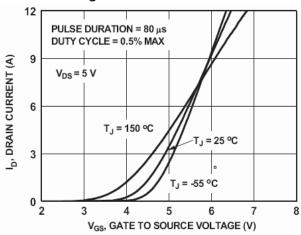
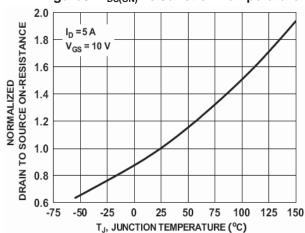


Figure 6. R_{DS(ON)} vs Junction Temperature





RATING AND CHARACTERISTICS CURVES (RM6N100S4V)

Figure 7. BV_{DSS} vs Junction Temperature

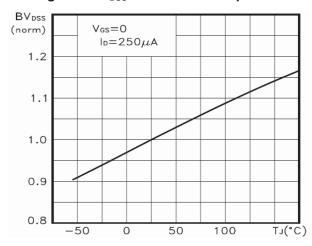


Figure 8. V_{GS(th)} vs Junction Temperature

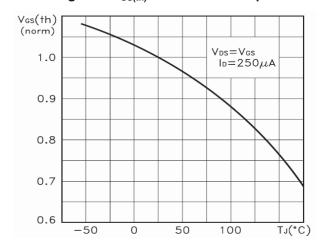


Figure9. Gate charge waveforms

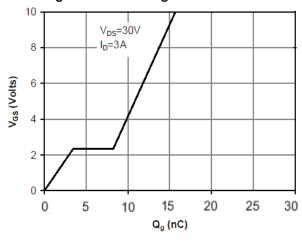
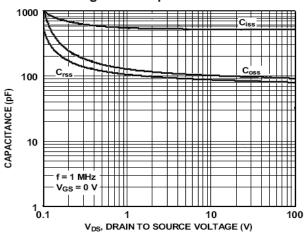


Figure 10. Capacitance



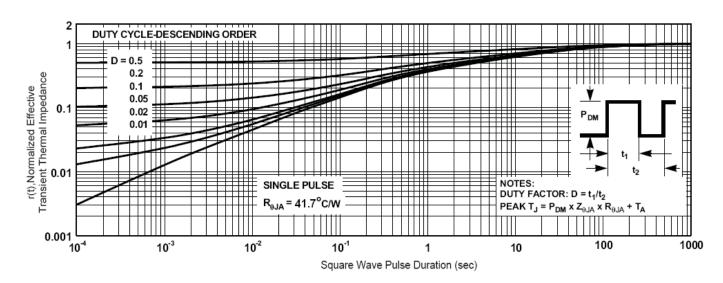
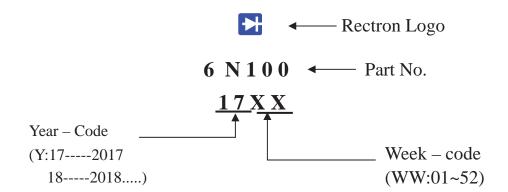


Figure 11. Normalized Maximum Transient Thermal Impedance



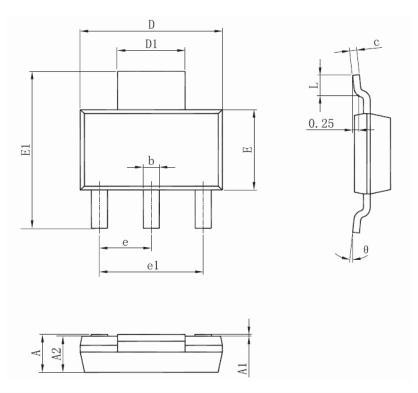


Marking on the body





SOT-223 Package Information



Comb a I	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
С	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
е	2.300	(BSC)	0.091(BSC)
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
θ	0°	10°	0°	10°

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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